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Irish Standard
I.S. EN 62739-3:2017

Test method for erosion of wave soldering equipment using molten lead-free solder alloy - Part 3: Selection guidance of erosion test methods

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This document is based on:	*Published:*
EN 62739-3:2017	2017-03-31

This document was published under the authority of the NSAI and comes into effect on:	ICS number:
2017-04-18	NOTE: If blank see CEN/CENELEC cover page

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I.S. EN 62739-3:2017 is the adopted Irish version of the European Document EN 62739-3:2017, Test method for erosion of wave soldering equipment using molten lead-free solder alloy - Part 3: Selection guidance of erosion test methods

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EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

EN 62739-3

March 2017

ICS 31.190; 31.240

English Version

Test method for erosion of wave soldering equipment using molten lead-free solder alloy - Part 3: Selection guidance of erosion test methods (IEC 62739-3:2017)

Méthode d'essai de l'érosion de l'équipement de brasage à la vague utilisant un alliage à braser sans plomb fondu - Partie 3: Document d'orientation pour le choix des méthodes d'essai d'érosion (IEC 62739-3:2017)

Verfahren zur Erosionsprüfung für Wellenlötausrüstungen bei Verwendung von geschmolzener, bleifreier Lotlegierung - Teil 3: Leitfaden für die Auswahl von Verfahren zur Erosionsprüfung (IEC 62739-3:2017)

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Comité Européen de Normalisation Electrotechnique
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Ref. No. EN 62739-3:2017 E

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European foreword

The text of document 91/1368/CDV, future edition 1 of IEC 62739-3, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62739-3:2017.

The following dates are fixed:

• latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement	(dop)	2017-11-10
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Annex ZA
(normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu

Publication	Year	Title	EN/HD	Year
IEC 60068-2-20	2008	Environmental testing - Part 2-20: Tests - Test T: Test methods for solderability and resistance to soldering heat of devices with leads	EN 60068-2-20	2008
IEC 61190-1-3	-	Attachment materials for electronic assembly - Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solders for electronic soldering applications	EN 61190-1-3	-
IEC 62739-1	2013	Test method for erosion of wave soldering equipment using molten lead-free solder alloy - Part 1: Erosion test method for metal materials without surface processing	EN 62739-1	2013
IEC 62739-2	-	Test method for erosion of wave soldering equipment using molten lead-free solder alloy - Part 2: Erosion test method for metal materials with surface processing	EN 62739-2	-

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IEC 62739-3

Edition 1.0 2017-01

INTERNATIONAL STANDARD

Test method for erosion of wave soldering equipment using molten lead-free solder alloy –
Part 3: Selection guidance of erosion test methods

IEC 62739-3:2017-01(en)

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IEC 62739-3

Edition 1.0 2017-01

INTERNATIONAL STANDARD

Test method for erosion of wave soldering equipment using molten lead-free solder alloy – Part 3: Selection guidance of erosion test methods

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

ICS 31.190; 31.240

ISBN 978-2-8322-3769-4

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

TEST METHOD FOR EROSION OF WAVE SOLDERING EQUIPMENT USING MOLTEN LEAD-FREE SOLDER ALLOY –

Part 3: Selection guidance of erosion test methods

FOREWORD

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International Standard IEC 62739-3 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this International Standard is based on the following documents:

The text of this standard is based on the following documents:

CDV	Report on voting
91/1368/CDV	91/1400/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

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A list of all the parts in the IEC 62739 series, under the general title *Test method for erosion of wave soldering equipment using molten lead-free solder alloy*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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TEST METHOD FOR EROSION OF WAVE SOLDERING EQUIPMENT USING MOLTEN LEAD-FREE SOLDER ALLOY –

Part 3: Selection guidance of erosion test methods

1 Scope

This part of IEC 62739 describes the selection methodology of an appropriate evaluating test method for the erosion of the metal materials without or with surface processing intended to be used for lead-free wave soldering equipment as a solder bath and other components which are in contact with the molten solder.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-2-20:2008, *Environmental testing – Part 2-20: Tests – Test T: Test methods for solderability and resistance to soldering heat of devices with leads*

IEC 61190-1-3, *Attachment materials for electronic assembly – Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solder for electronic soldering applications*

IEC 62739-1:2013, *Test method for erosion of wave soldering equipment using molten lead-free solder alloy – Part 1: Erosion test method for metal materials without surface processing*

IEC 62739-2, *Test method for erosion of wave soldering equipment using molten lead-free solder alloy – Part 2: Erosion test method for metal materials with surface processing*

3 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at http://www.electropedia.org/
- ISO Online browsing platform: available at http://www.iso.org/obp

3.1
erosion
phenomenon where a base material is dissolved and made thinner by coming into contact with molten solder

[SOURCE: IEC 62739-1:2013, 3.1]

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